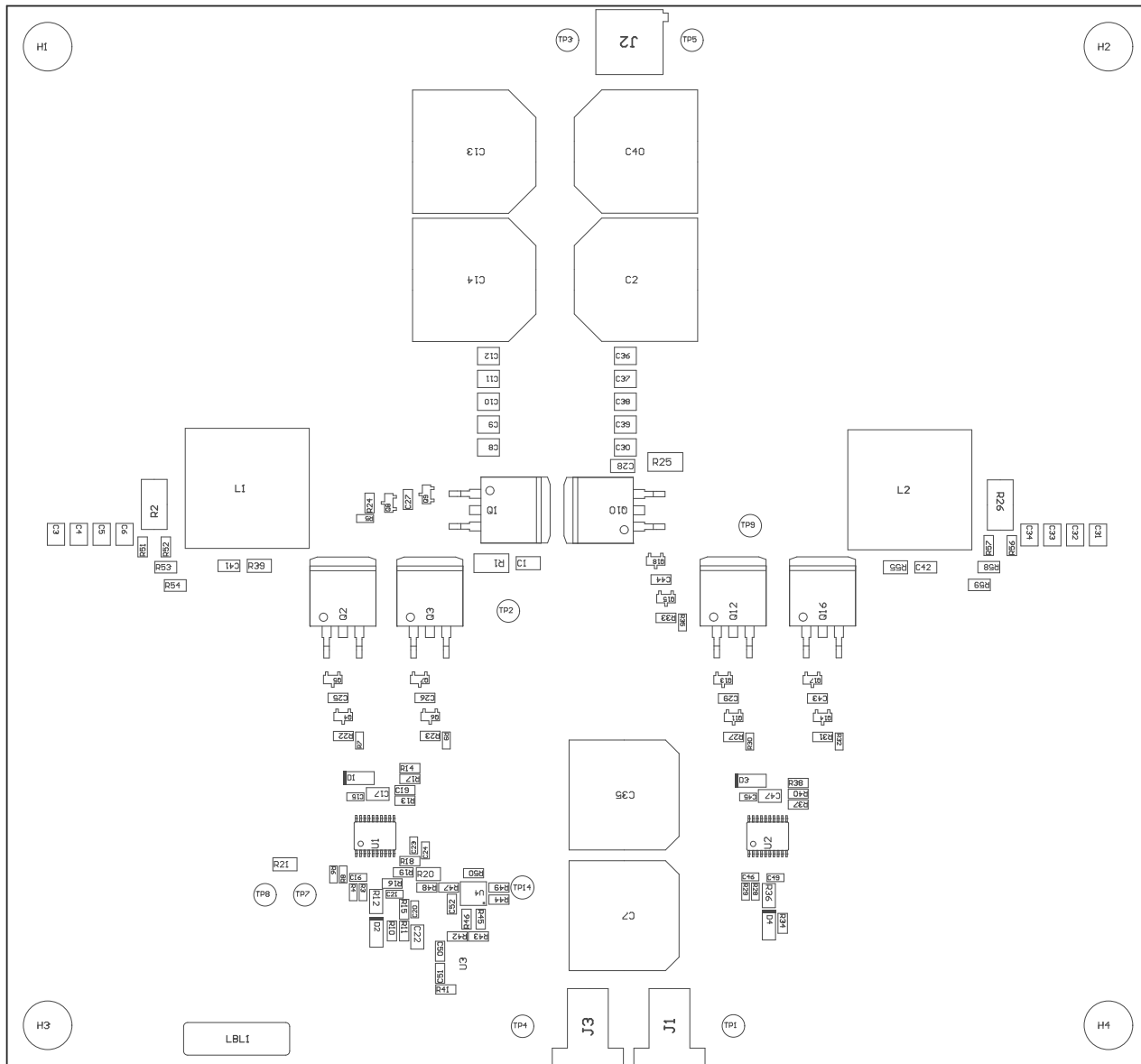


ZZ1 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ3 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

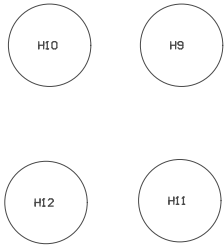
ZZ4 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



ZZ2 ■These assemblies are ESD sensitive, ESD precautions shall be observed.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP9309	REV: Rev3CSUN REV: Not In VersionControl
IGNORE ->		
PLOT NAME = Top Assembly Drawing	GENERATED : 9/23/2015 2:06:20 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP9309	REV: Rev3C	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 9/23/2015	2:06:20 PM	TEXAS INSTRUMENTS

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